

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPD70N03S4L-04	**Issued**	27. April 2022
MA#	MA005738174		
Package	PG-TO252-3-11	**Weight***	370.59 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.552	0.42	0.42	4189	4189
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		174	
	non noble metal	iron	7439-89-6	0.215	0.06		581	
	non noble metal	copper	7440-50-8	215.017	58.01	58.09	580202	580957
wire	non noble metal	aluminium	7429-90-5	3.285	0.89	0.89	8863	8863
encapsulation	inorganic material	zincoxide	1314-13-2	1.258	0.34		3393	
	miscellaneous	miscellaneous	-	6.288	1.70		16967	
	plastics	epoxy resin	-	18.864	5.09		50902	
	inorganic material	silicondioxide	60676-86-0	99.349	26.81	33.94	268084	339346
leadfinish	non noble metal	tin	7440-31-5	3.740	1.01	1.01	10092	10092
plating	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	245	246
solder	non noble metal	tin	7440-31-5	0.033	0.01		90	
	noble metal	silver	7440-22-4	0.042	0.01		112	
	non noble metal	lead	7439-92-1	1.589	0.43	0.45	4289	4491
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			16	
	non noble metal	iron	7439-89-6	0.019	0.01		52	
	non noble metal	copper	7440-50-8	19.177	5.17	5.18	51748	51816
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com